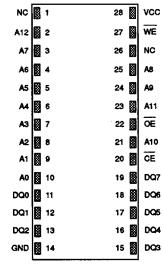


DS1225D/E 64K Nonvolatile SRAM

FEATURES

- Data retention in the absence of V_{CC}
- · Data is automatically protected during power loss
- Directly replaces 8K x 8 volatile static RAM or EEPROM
- Unlimited write cycles
- Low-power CMOS
- Over 10 years of data retention
- Standard 28-pin JEDEC pinout
- Available in 70, 85, 100, or 120 ns read access times
- · Read cycle time equals write cycle time
- Optional ±5% and ±10% operating range
- Optional industrial temperature range of -40°C to +85°C, designated IND

PIN ASSIGNMENT



28-Pin Encapsulated Package (740 Mil Flush Bottom)

PIN DESCRIPTION

A0 - A12 - Address Inputs CE - Chip Enable **GND** - Ground DQ0-DQ7 - Data In/Data Out V_{CC} - Power (+5V) WE Write Enable OE - Output Enable NC - No Connect

NOTE: Pins 1 & 26 missing by design

DESCRIPTION

The DS1225D and DS1225E are 65,536-bit, fully static, nonvolatile RAMs organized as 8192 words by 8 bits. Each NV SRAM has a self-contained lithium energy source and control circuitry that constantly monitors V_{CC} for an out-of-tolerance condition. When such a condition occurs, the lithium energy source automatically switches on and write protection is unconditionally enabled to prevent garbled data. The NV SRAM can be

used in place of existing 8Kx 8 SRAMs directly conforming to the popular bytewide 28-pin DIP standard. The DS1225D/E also matches the pinout of the 2764 EPROM or the 2864 EEPROM, allowing direct substitution while enhancing performance. There is no limit on the number of write cycles that can be executed and no additional support circuitry is required for microprocessor interface.

OPERATION

READ MODE

The DS1225D/E executes a read cycle whenever WE (Write Enable) is inactive (high) and $\overline{\text{CE}}$ (Chip Enable) is active (low). The unique address specified by the 13 address inputs (A0-A12) defines which of the 8192 bytes of data is to be accessed. Valid data will be available to the eight data output drivers within t_{ACC} (Access Time) after the last address input signal is stable, providing that $\overline{\text{CE}}$ and $\overline{\text{OE}}$ (Output Enable) access times are also satisfied. If $\overline{\text{OE}}$ and $\overline{\text{CE}}$ access times are not satisfied, then data access must be measured from the later occurring signal ($\overline{\text{CE}}$ or $\overline{\text{OE}}$) and the limiting parameter is either t_{CO} for $\overline{\text{CE}}$ or t_{OE} for $\overline{\text{OE}}$ rather than address access.

WRITE MODE

The DS1225D/E are in the write mode whenever the WE and CE signals are in the active (low) state after address inputs are stable. The latter occurring falling edge of CE or WE will determine the start of the write cycle. The write cycle is terminated by the earlier rising edge of CE or WE. All address inputs must be kept valid throughout the write cycle. WE must return to the high

ABSOLUTE MAXIMUM RATINGS*

Voltage on Any Pin Relative to Ground Operating Temperature Storage Temperature Soldering Temperature state for a minimum recovery time (t_{WR}) before another cycle can be initiated. The \overline{OE} control signal should be kept inactive (high) during write cycles to avoid bus contention. However, if the output bus has been enabled (\overline{CE} and \overline{OE} active) then \overline{WE} will disable the outputs in t_{ODW} from its falling edge.

DATA RETENTION MODE

The DS1225E provides full functional capability for V_{CC} greater than 4.75 volts and write protects at 4.5 volts. The DS1225D provides full functional capability for V_{CC} greater than 4.5 volts and write protects by 4.25 volts. Data is maintained in the absence of V_{CC} without any additional support circuitry. The DS1225D/E constantly monitors V_{CC}. Should the supply voltage decay, the RAM automatically write protects itself. All inputs to the RAM become "don't care" and all outputs are high impedance. As V_{CC} falls below approximately 3.0 volts, the power switching circuit connects the lithium energy source to RAM to retain data. During power-up, when V_{CC} rises above approximately 3.0 volts, the power switching circuit connects external V_{CC} to the RAM and disconnects the lithium energy source. Normal RAM operation can resume after V_{CC} exceeds 4.5 volts for the DS1225D and 4.75 volts for the DS1225E.

-0.3V to +7.0V 0°C to +70°C; -40°C to +85°C for IND parts -40°C to +70°C; -40°C to +85°C for IND parts 260°C for 10 seconds

* This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operation sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods of time may affect reliability.

RECOMMENDED DC OPERATING CONDITIONS

(0°C to 70°C)

PARAMETER	SYMBOL	MIN	TYP	MAX	UNITS	NOTES
DS1225D Power Supply Voltage	V _{CC}	4.50	5.0	5.5	V	
DS1225E Power Supply Voltage	Vcc	4.75	5.0	5.25	٧	
Logic 1	V _{IH}	2.2	1	V _{CC}	V	
Logic 0	V _{IL}	0.0		+0.8	V	

DC ELECTRICAL CHARACTERISTICS

(0°C to 70°C; V_{CC} =5V ± 10% for DS1225D) (0°C to 70°C; V_{CC} =5V ± 5% for DS1225E)

	(0 0 10 10 0, 000-01 2 0 10 10 10 10 10 10 10 10 10 10 10 10 1						
PARAMETER	SYMBOL	MIN	TYP	MAX	UNITS	NOTES	
Input Leakage Current	I _{IL}	-1.0		+1.0	μА		
I/O Leakage Current CE>V _{IH} <v<sub>CC</v<sub>	lo	-1.0		+1.0	μА		
Output Current @2.4V	Юн	-1.0			mA		
Output Current @0.4V	loL	2.0			mA		
Standby Current CE = 2.2V	I _{CCS1}		5.0	10.0	mA		
Standby Current $\overline{CE} = V_{CC}-0.5V$	I _{CCS2}		3.0	5.0	mA		
Operating Current t _{CYC} =100ns (Commercial)	I _{CC01}			75	mA		
Operating Current t _{CYC} =100ns (Industrial)	I _{CC01}			85	mA		
Write Protection Voltage (DS1225D)	V _{TP}	4.50	4.62	4.75	V		
Write Protection Voltage (DS1225E)	V _{TP}	4.25	4.37	4.5	V		

DC TEST CONDITIONS

Outputs Open

All Voltages Are Referenced to Ground.

CAPACITANCE

 $(t_A = 25^{\circ}C)$

PARAMETER	SYMBOL	MIN	TYP	MAX	UNITS	NOTES
Input Capacitance	CIN		5	10	pF	
Input/Output Capacitance	CVO	, and the second	5	10	рF	

AC ELECTRICAL CHARACTERISTICS

(0°C to 70°C; V_{CC} =5.0V + 10% for DS1225D) (0°C to 70°C; V_{CC} =5.0V \pm 5% for DS1225E)

	_	DS12	25 D/E-70	DS1225D/E-85			DS1225D/E-100 DS1225D/E-120				
PARAMETER	SYM	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	UNITS	NOTES
Read Cycle Time	t _{RC}	70		85		100		120		ns	
Access Time	tACC		70		85		100		120	ns	
OE to Output Valid	t _{OE}		35		45		50		60	ns	
CE to Output Valid	t∞		70		85	_	100		120	ns	
OE or CE to Output Active	t _{COE}	5		5		5		5		ns	5
Output High Z from Deselection	top		25		25		25		25	ns	5
Output Hold from Address Change	ф	5		5		5		5		ns	
Write Cycle Time	twc	70		85		100		120		ns	
Write Pulse Width	t _{WP}	55		65		75		90		ns	3
Address Setup Time	t _{AW}	0		0		0		0		ns	
Write Recovery Time	t _{WR}	10		10		10		10		ns	
Output High Z from WE	wao [‡]		25		25		25	_	25	ns	5
Output Active from WE	t _{OEW}	5		5		5		5		ns	5
Data Setup Time	t _{DS}	30		35		40		50		ns	4
Data Hold Time	toH	10		10		10		10		ns	4

AC TEST CONDITIONS

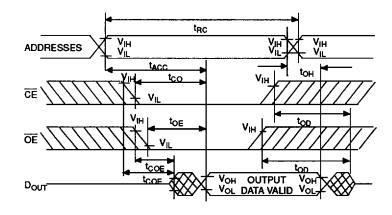
Output Load: 100 pF + 1TTL Gate input Pulse Levels: 0 - 3.0V

Timing Measurement Reference Levels

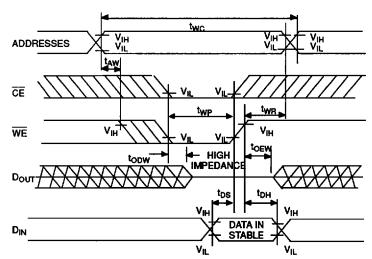
Input: 1.5V Output: 1.5V

Input Pulse Rise and Fall Times: 5ns

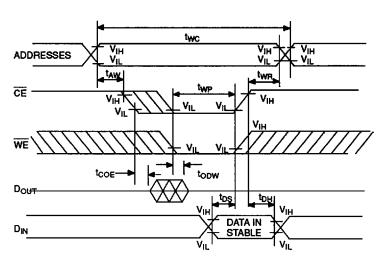
READ CYCLE (1)



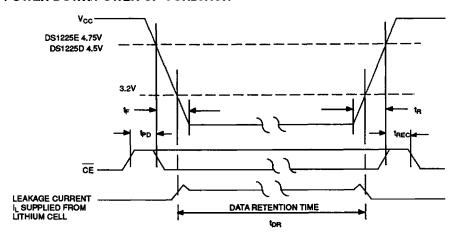
WRITE CYCLE 1 (2), (6), (7)



WRITE CYCLE 2 (2), (8)



POWER-DOWN/POWER-UP CONDITION



POWER-DOWN/POWER-UP TIMING

SYM	PARAMETER	MIN	MAX	UNITS	NOTES
t _{PD}	CE at V _{IH} before Power-Down	0		με	10
t _F	V _{CC} Slew from 4.75V to 0V (CE at V _{IH})	300		με	DS1225E
t _F	V _{CC} Siew from 4.5V to 0V (CE at V _{IH})	300		με	DS1225D
t _R	V _{CC} Slew from 0V to 4.75V (CE at V _{IH})	0		μs	DS1225E
t _R	V _{CC} Slew from 0V to 4.5V (CE at V _{IH})	0		μs	DS1225D
t _{REC}	CE at V _{IH} after Power-Up	2	125	ms	

 $(t_A = 25^{\circ}C)$

SYM	PARAMETER	MIN	MAX	UNITS	NOTES
t _{DR}	Expected Data Retention Time	10		years	9

WARNING:

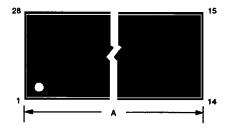
Under no circumstance are negative undershoots, of any amplitude, allowed when device is in battery backup mode.

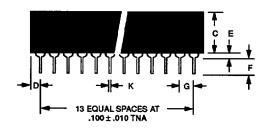
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NOTES

- 1. WE is high for a Read Cycle.
- 2. $\overline{OE} = V_{IH}$ or V_{IL} . If $\overline{OE} = V_{IH}$ during write cycle, the output buffers remain in a high impedance state.
- 3. two is specified as the logical AND of CE and WE. two is measured from the latter of CE or WE going low to the earlier of CE or WE going high.
- t_{DH}, t_{DS} are measured from the earlier of CE or WE going high.
- 5. These parameters are sampled with a 5 pF load and are not 100% tested.
- If the CE low transition occurs simultaneously with or later than the WE low transition in write cycle 1, the output buffers remain in a high impedance state during this period.
- 7. If the CE high transition occurs prior to or simultaneously with the WE high transition in write cycle 1, the output buffers remain in a high impedance state during this period.
- 8. If WE is low or the WE low transition occurs prior to or simultaneously with the CE low transition, the output buffers remain in a high impedance state during this period.
- Each DS1225D/E is marked with a 4-digit date code AABB. AA designates the year of manufacture. BB designates the week of manufacture. The expected tops is defined as starting at the date of manufacture.
- In a power down condition the voltage on any pin may not exceed the voltage on V_{CC}.

DS1225D/E NONVOLATILE SRAM 28-PIN 740 MIL MODULE





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PKG	28-PIN					
DiM	MIN	MAX				
A IN. MM	1.520 38.61	1.540 39.12				
B IN. MM	0.695 17.65	0.720 18.29				
C IN.	0.350 8.89	0.375 9.53				
D IN. MM	0.100 2.54	0.130 3.30				
E IN.	0.015 0.38	0.035 0.89				
F IN.	0.110 2.79	0.140 3.56				
G IN.	0.090 2.29	0.110 2.79				
H IN. MM	0.590 14.99	0.630 16.00				
J IN.	0.008 0.20	0.012 0.30				
K IN. MM	0.015 0.38	0.021 0.53				